

## ElectroStatic Discharged Protection Devices (ESD) Data Sheet

### Description

The LAQ02C03L01 of Transient Voltage Suppressors (TVS) is designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, MP3 player and digital cameras. It offer superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs. It is designed to protect sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD), lightning, electrical fast transients (EFT), and cable discharge events (CDE).

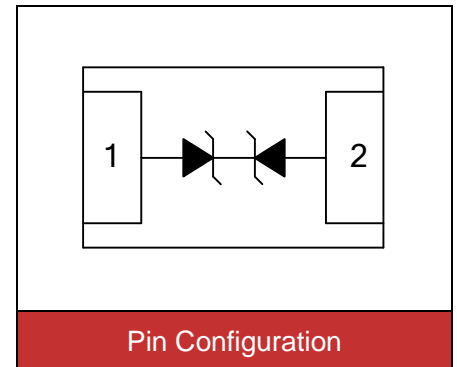


Contact : ±30kV  
Air : ±30kV



### Features

- IEC61000-4-2 ESD 30KV Air, 30KV contact compliance
- 0201 surface mount package
- Working voltage: 3.3V
- Low leakage current
- Low operating and clamping voltages
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260-270°C
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020
- Marking: C3



### Maximum Ratings

Rating	Symbol	Value	Unit
ESD voltage (Contact discharge)	$V_{ESD}$	±30	kV
ESD voltage (Air discharge)		±30	
Lead soldering temperature	$T_L$	260	°C
Storage & operating temperature range	$T_{STG}, T_J$	-55~+150	°C

**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ )**

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	$V_{RWM}$				3.3	V
Reverse breakdown voltage	$V_{BR}$	$I_{BR}=1\text{mA}$	3.5			V
Reverse leakage current	$I_R$	$V_R=3.3\text{V}$			1	$\mu\text{A}$
Clamping voltage ( $t_p=8/20\mu\text{s}$ )	$V_C$	$I_{PP}=7\text{A}$		10		V
Peak Pulse Current ( $t_p=8/20\mu\text{s}$ )	$I_{PP}$				7	A
Off state junction capacitance	$C_J$	$0\text{Vdc}, f=1\text{MHz}$		15		pF

**Typical Characteristics Curves**

Figure 1. Pulse Waveforms

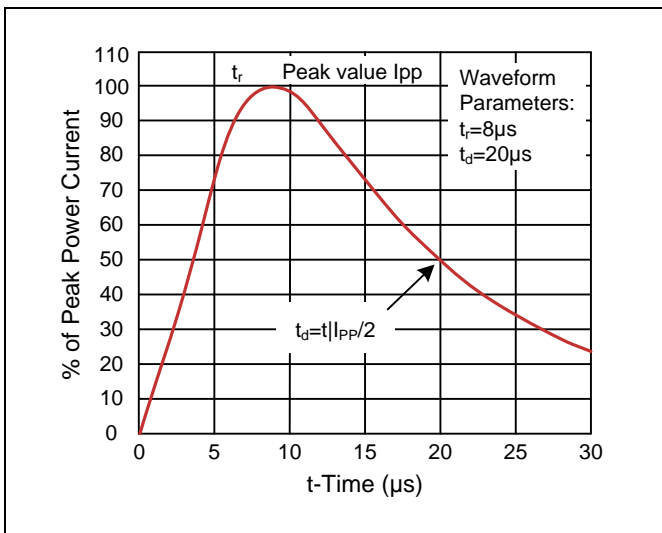


Figure 2. Clamping Voltage vs. Peak Pulse Current

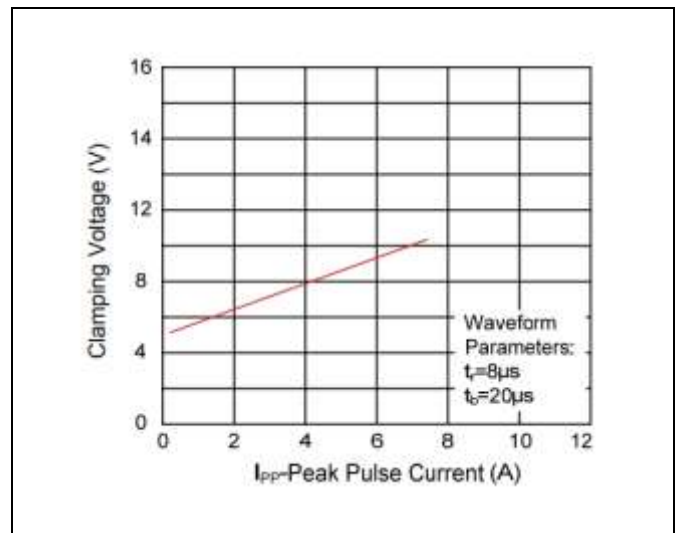


Figure 3. Capacitance vs. Reverse Voltage

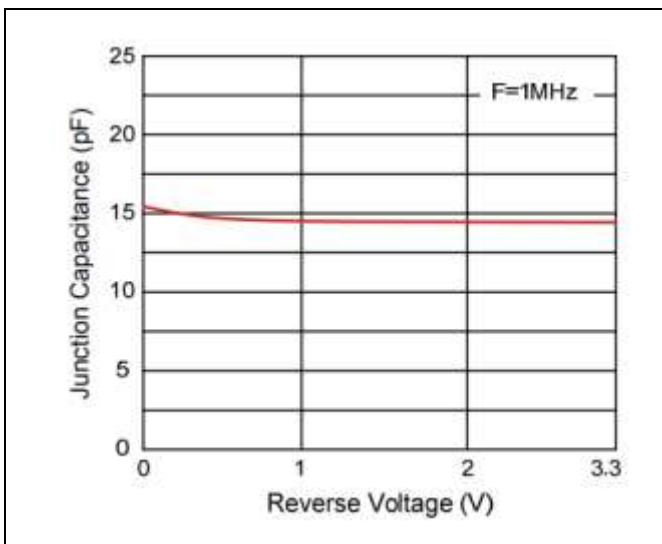
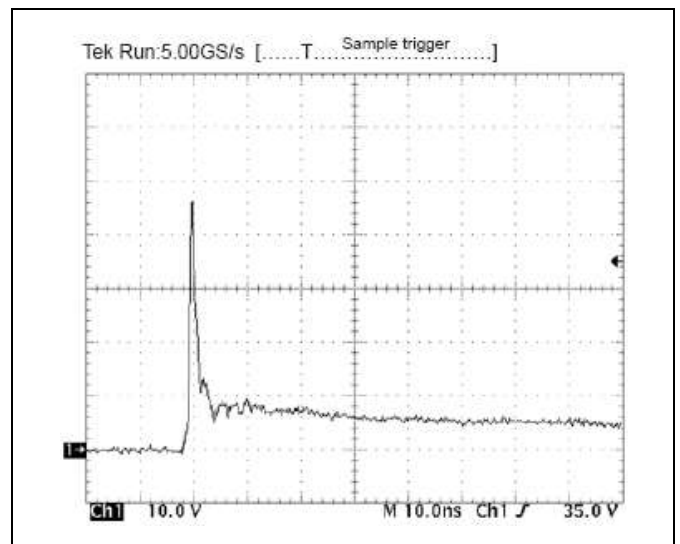
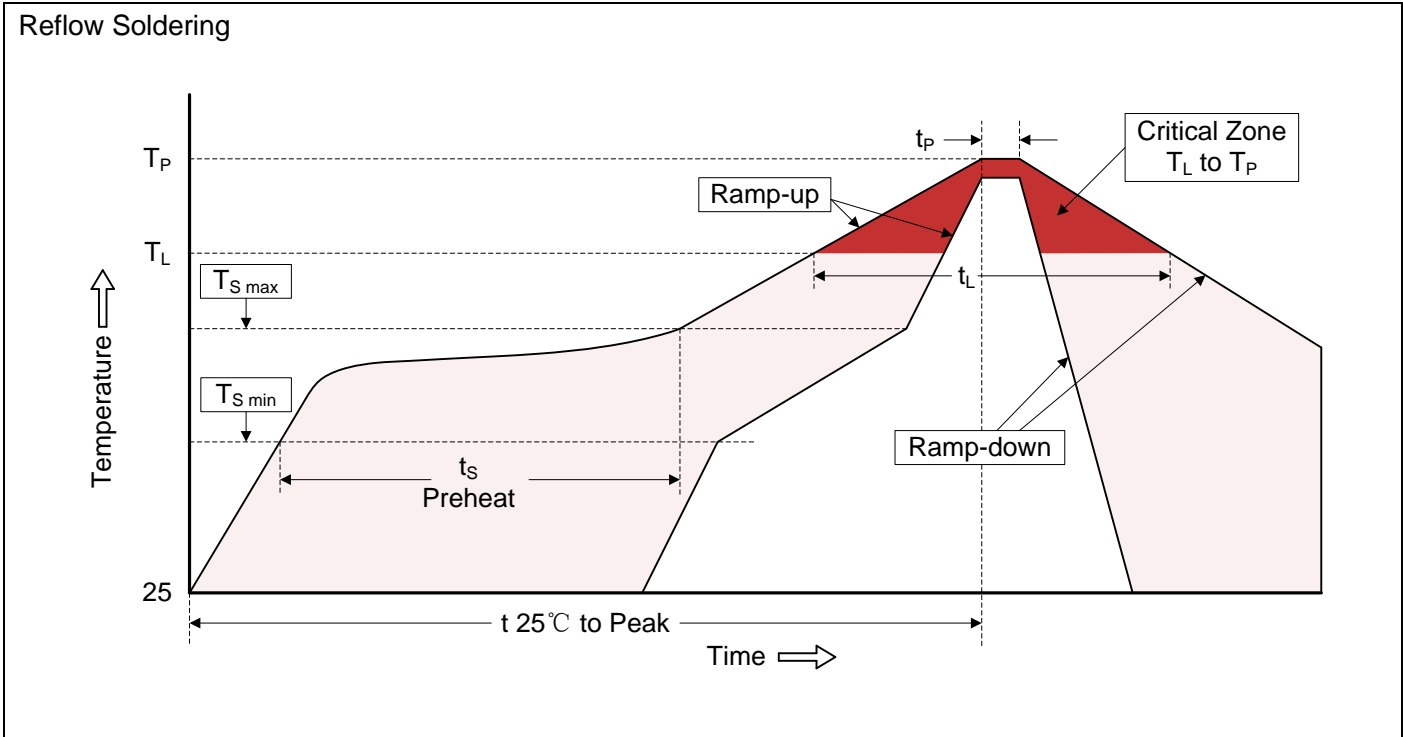


Figure 4. ESD Clamping(8kV Contact IEC61000-4-2)



**Recommended Soldering Conditions**



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate ( $T_L$ to $T_P$ )	3°C/second max.
Preheat -Temperature Min ( $T_{S \min}$ ) -Temperature Max ( $T_{S \max}$ ) -Time (min to max) ( $t_s$ )	150°C 200°C 60-180 seconds
$T_{S \max}$ to $T_L$ -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature ( $T_L$ ) -Time ( $t_L$ )	217°C 60-150 seconds
Peak Temperature ( $T_P$ )	260°C
Time within 5°C of actual Peak Temperature ( $t_P$ )	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

**Dimensions (0201)**

Symbol	Dimension (mm)			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.57	0.63	0.022	0.025
B	0.27	0.33	0.011	0.013
C	0.22	0.28	0.009	0.011
D	0.12	0.18	0.005	0.007
E	0.40		0.016	
F	0.24	0.30	0.009	0.012
G	-	0.01	-	0.0004

**Packaging**

Symbol	Dimension (mm)
W	8.00±0.30
P0	4.00±0.10
P1	2.00±0.10
P2	2.00±0.10
D0	Φ1.55±0.10
D1	Φ0.20±0.05
E	1.75±0.10
F	3.50±0.10
A	0.50±0.10
B	0.75±0.10
K	0.40±0.05
t	0.20±0.05
D	Φ178.0±2.0
D2	Φ13.0
W1	9.5
Quantity: 10000PCS	